Materials Declaration

Package	LQFP
Body Size	14 X 14
LeadCount	64
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.67 E-02	29612
SiO2 Filler	86	1.79 E-01	318326
Phenol Resin	5	1.04 E-02	18507
Antimony_Sb2O3	0.4	8.35 E-04	1481
Brominated Resin	0.4	8.35 E-04	1481
Carbon Black	0.2	4.17 E-04	740

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.07 E-01	366702
Ni	3	6.45 E-03	11436
Si	0.65	1.40 E-03	2478
Mg	0.15	3.22 E-04	572

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	1419

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	4.88 E-03	8656

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.95 E-03	3451

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.21 E-01	214498

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	3.03 E-03	5367
Ag Filler	74	8.61 E-03	15275

Package Totals

Weight (g)	PPM
5.64 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-C

Note: The information provided in this declaration are true to the best of ADI's knowledge.
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Materials Declaration

Package	LQFP
Body Size	14 X 14
LeadCount	64
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.67 E-02	29612
SiO2 Filler	86	1.79 E-01	318326
Phenol Resin	5	1.04 E-02	18507
Antimony_Sb2O3	0.4	8.35 E-04	1481
Brominated Resin	0.4	8.35 E-04	1481
Carbon Black	0.2	4.17 E-04	740

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	2.07 E-01	366702
Ni	3	6.45 E-03	11436
Si	0.65	1.40 E-03	2478
Mg	0.15	3.22 E-04	572

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	1419

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.15 E-03	7358
Pb	15	7.32 E-04	1298

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.95 E-03	3451

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.21 E-01	214498

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	3.03 E-03	5367
Ag Filler	74	8.61 E-03	15275

Package Totals

Weight (g)	PPM
5.64 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-A

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